

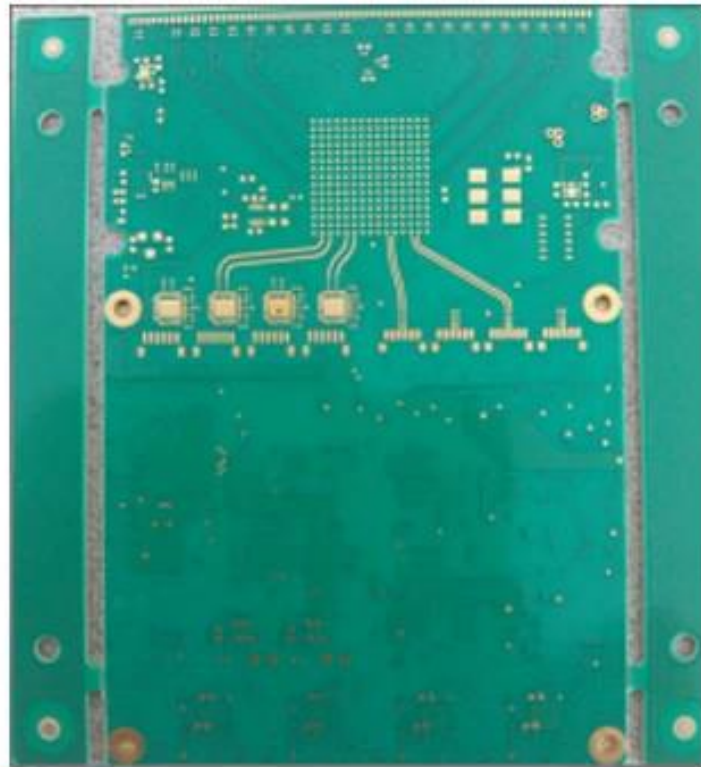
COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED

This PN required 10% impedance, 8mil laser drill, POFV, stacked via, laser blind via drill thru 6mil dielectric and plug and plating flat via

Pack with colorless transparent bubble film ,25 PCS/ bag, put desiccant in flank, put humidity indicator card on top side

Layer structure

Custom Info Lyr	Image	Foil	Name
COMP 6+/-0.9mil		0.5oz	Foil 1/2oz(RTF)
			R-5670K 1080 RC64%
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L2 3.9+/-0.7mil		0.5oz	Foil 1/2oz(RTF)
			R-5670K 3313 RC54%
L3 L4		0.5oz	
		0.5oz	R-5775K 0.200mm H/H 42.5"49"(3313*2)(RTF)
6.9+/-1.5mil			R-5670K 1080 RC64%
			R-5670K 3313 RC54%
L5 L6		0.5oz	
		0.5oz	R-5775K 0.100mm H/H 42.5"49"(3313*1)(RTF)
6.9+/-1.5mil			R-5670K 3313 RC54%
			R-5670K 1080 RC64%
L7 L8		0.5oz	
		0.5oz	R-5775K 0.200mm H/H 42.5"49"(3313*2)(RTF)
3.9+/-0.7mil			R-5670K 3313 RC54%
L9		0.5oz	Foil 1/2oz(RTF)
			R-5670K 1080 RC64%
6+/-0.9mil			R-5670K 1080 RC64%
SOLD		0.5oz	Foil 1/2oz(RTF)





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